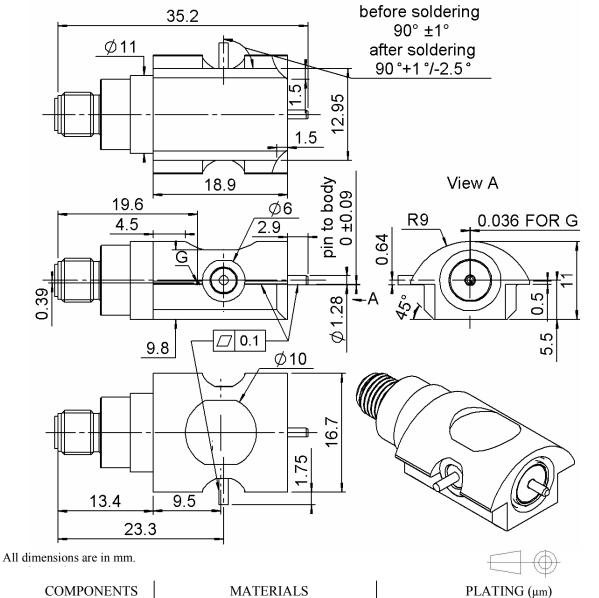
SMA SWITCH EDGE CARD SMT RIGHT TYPE

PACKAGING IN REEL 110

R124.422.001

Series: SMA-COM



COMPONENTS	MATERIALS	PLATING (µm)	
BODY CENTER CONTACT OUTER CONTACT INSULATOR GASKET OTHERS PARTS	BRASS BERYLIUM COPPER BRASS PEEK BRASS	NPGR,BBR 2 NPGR BBR 2 NPGR	
-	-	-	

Issue: 1030 A



50 W at 1.8 GHz

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PACKAGING

Standard Unit Other 110 'W' option Contact us

SPECIFICATION

ELECTRICAL CHARACTERISTICS

Impedance	50	Ω
Frequency	DC-3	GHz

VSWR
Isolation at DC to 1 GHz
Isolation at 1 to 2 GHz
Isolation at 2 to 3 GHz
Insertion loss at DC to 1 GHz
Insertion loss at 1 to 2 GHz
Insertion loss at 2 to 3 GHz

RF leakage - (NA - F(GHz)) dB Maxi Voltage rating 300 Veff Maxi

Dielectric withstanding voltage Insulation resistance S00 Veff mini S000 M Ω mini Power withstanding S0 W at 0.9 GHz

ENVIRONMENTAL

Operating temperature
Hermetic seal
Panel leakage

-40/+85 ° C
NA Atm.cm3/s
NA

OTHER CHARACTERISTICS

Assembly instruction NA

Others:

Action Mating force

20N MAX

15N min

MECHANICAL CHARACTERISTICS

Center contact retention

Axial force – Mating end
Axial force – Opposite end
Torque

NA N mini
NA N mini
NA N.cm mini

Axial force side pin (1)

Recommended torque

Mating NA N.cm Panel nut NA N.cm

Mating life 100 Cycles mini

Weight 22.0700 g

(1)Do not apply force on the center contact before mounting the switch on PCB

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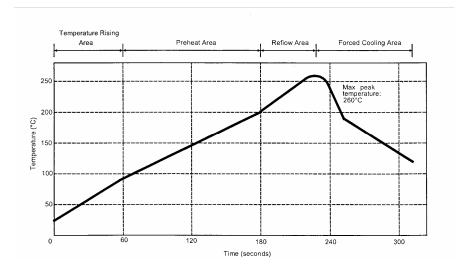
Series: SMA-COM

SOLDER PROCEDURE

- 1. Deposit solder paste 'Sn Ag4 Cu0.5' on mounting zone by screen printing application. We recommend a low residue flux.
 - We advise a thickness of 150 microm (5.850 microinch). Verify that the edges of the zone are clean.
- 2. Placement of the receptacle on the mounting zone with an automatic machine of 'pick and place' type. A video camera is recommended for positioning of the component. Adhesive agents must not be used on the receptacle.
- 3. This process of soldering has been tested with convection oven .Below please find ,the typical profile to use.
- 4. The cleaning of printed circuit boards is not obliged .
- 5. Verification of solder joints and position of the component by visual inspection.

NOTE: The receptacle and the plug must not be mated before completion of this procedure

TEMPERATURE PROFILE



Parameter	Value	Unit
Temperature rising Area	1 - 4	°C/sec
Max Peak Temperature	260	°C
Max dwell time @260°C	10	sec
Min dwell time @235°C	20	sec
Max dwell time @235°C	60	sec
Temperature drop in cooling Area	-1 to - 4	°C/sec
Max dwell time above 100°C	420	sec

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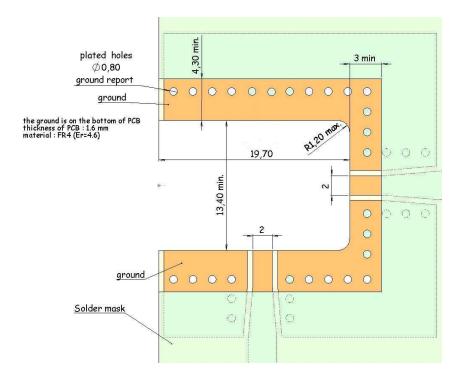


SMA SWITCH EDGE CARD SMT RIGHT TYPE PACKAGING IN REEL 110

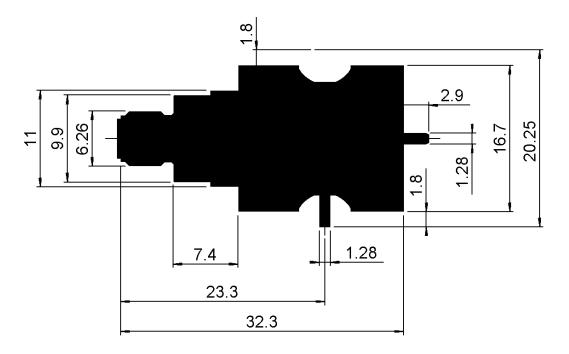
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PCB for SMA switch



Shadow of SMA switch for video camera



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In the effort to improve our products, we reserve the right to make changes judged to be

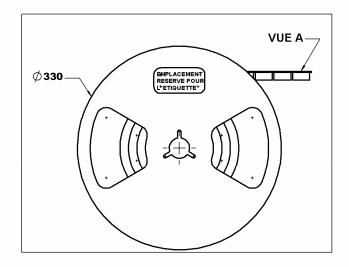
necessary.



SMA SWITCH EDGE CARD SMT RIGHT TYPE PACKAGING IN REEL 110

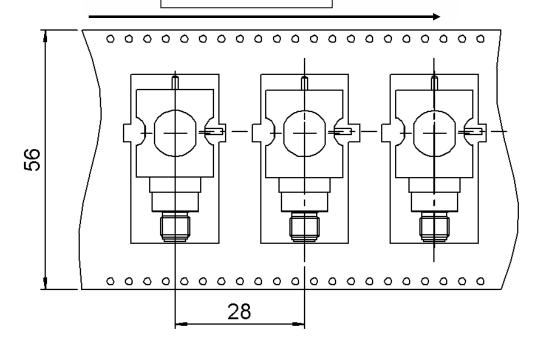
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bobine Ech: 0.7

TAPE FEED DIRECTION



VUE A

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